

# High performance CMOS: gate-stack engineering

## LECTURE 22

- the effect of  $C_{ox}$  on leakage and ON currents
- high-k dielectrics
- tunneling through the oxide
- the importance of electron affinity
- metal gates

ON current:

$$I_{Dsat} = ZC_{ox}(V_{GS} - V_T) \cdot v_{sat} \frac{\sqrt{1 + 2\mu_{eff}(V_{GS} - V_T)/(mv_{sat}L)} - 1}{\sqrt{1 + 2\mu_{eff}(V_{GS} - V_T)/(mv_{sat}L)} + 1}$$

Break this down into charge and velocity.

A high  $C_{ox}$  is needed to get more charge in the channel.

OFF Current:

A high  $C_{ox}$  is needed to get a steeper inverse sub-threshold slope

$$S = \left( \frac{\partial \log_{10} I_D}{\partial V_{GS}} \right)^{-1} \equiv 2.303m V_{th}$$

$$m(0) = 1 + \frac{\gamma}{2\sqrt{2\phi_B + V_{SB}}} \equiv 1 + \frac{C_b(0)}{C_{ox}}$$

# Relation between $m$ and $C_b(0)$

10.3

CAMPAD

From (10.43)  $m = 1 + \frac{\gamma}{2\sqrt{2\phi_B + V_{SB}}}$  where  $\gamma = \frac{\sqrt{2q\epsilon_s NA}}{C_{ox}}$

$$C_b = \frac{\epsilon_s}{W} = \frac{\epsilon_s}{\sqrt{\frac{2\epsilon_s}{q} \frac{2\phi_B}{NA}}} \quad @ \quad \psi_s = 2\phi_B \rightarrow C_b = \frac{1}{\sqrt{2}} \sqrt{\frac{\epsilon_s q NA}{2\phi_B}}$$

$$= \frac{1}{2} \sqrt{\frac{2\epsilon_s q NA}{2\phi_B}}$$

$$\therefore \gamma C_{ox} = 2 C_b \sqrt{2\phi_B}$$

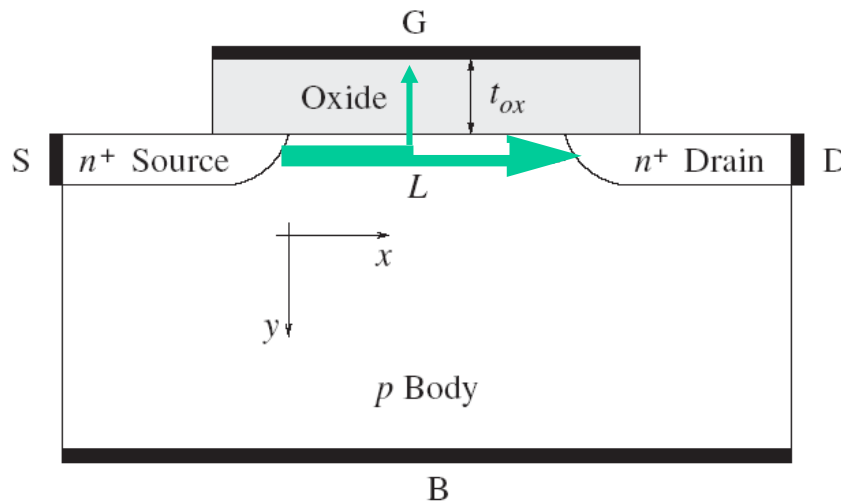
and  $m = 1 + \frac{C_b}{C_{ox}}$

as per (10.36), provided  $\psi_s = 2\phi_B$ , as would be the case in strong inversion at the source and when  $V_{SB} = 0$ .

Leakage current:

$$C_{ox} = \frac{\epsilon_{ox}}{t_{ox}}$$

There's a limit to how far  $t_{ox}$  can be reduced before channel-gate leakage occurs



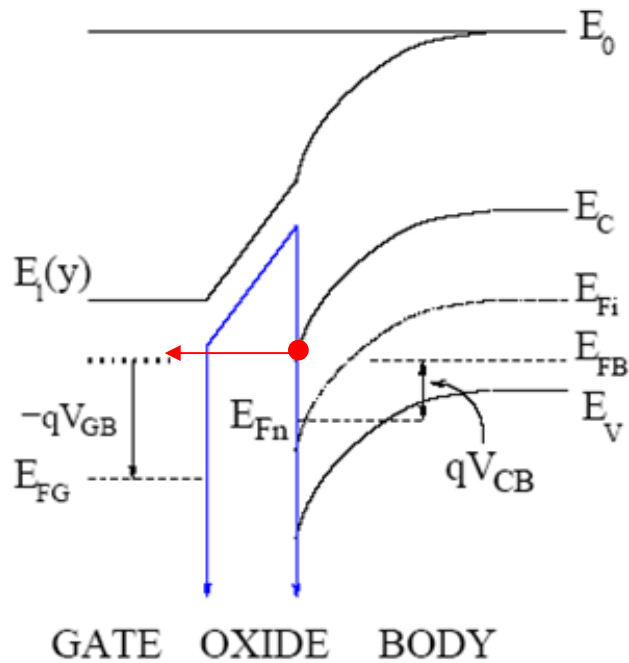
# High-k dielectrics

$$C_{ox} = \frac{\epsilon_{ox}}{t_{ox}}$$

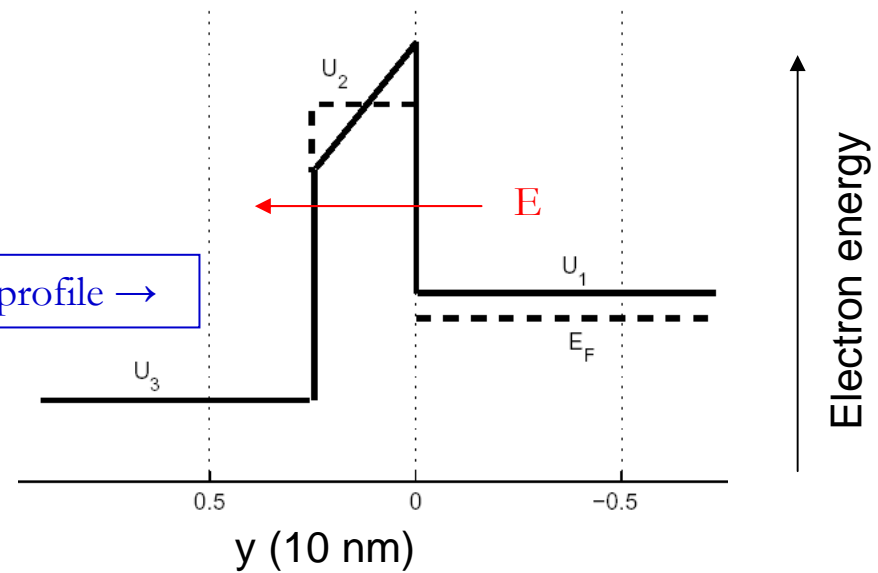
- High  $C_{OX}$  needed for  $I_D$  and  $S$
- High  $t_{OX}$  needed to reduce gate leakage
- Resolve conflict by increasing  $\epsilon$

<i>Dielectric</i>	<i>Dielectric constant (bulk)</i>
Silicon dioxide ( $SiO_2$ )	3.9
Silicon nitride ( $Si_3N_4$ )	7
Aluminum oxide ( $Al_2O_3$ )	~10
Tantalum pentoxide ( $Ta_2O_5$ )	25
Lanthanum oxide ( $La_2O_3$ )	~21
Gadolinium oxide ( $Gd_2O_3$ )	~12
Yttrium oxide ( $Y_2O_3$ )	~15
Hafnium oxide ( $HfO_2$ )	~20
Zirconium oxide ( $ZrO_2$ )	~23

# Tunneling through the oxide



Simplify the U profile  $\rightarrow$



Solve SWE in each region:

write as:

$$k_1 = \frac{1}{\hbar} \sqrt{2m_1^*(E - U_1)}$$

$$k_2 = \frac{1}{\hbar} \sqrt{2m_2^*(E - U_2)} \equiv ik'_2$$

$$k'_2 = \frac{1}{\hbar} \sqrt{2m_2^*(U_2 - E)}$$

$$k_3 = \frac{1}{\hbar} \sqrt{2m_3^*(E - U_3)}.$$

## Sec. 5.7.2

Solutions for  $\psi \psi^*$ 

$$\psi_1 = Ae^{ik_1y} + Be^{-ik_1y}$$

$$\psi_2 = Ce^{k'_2y} + De^{-k'_2y}$$

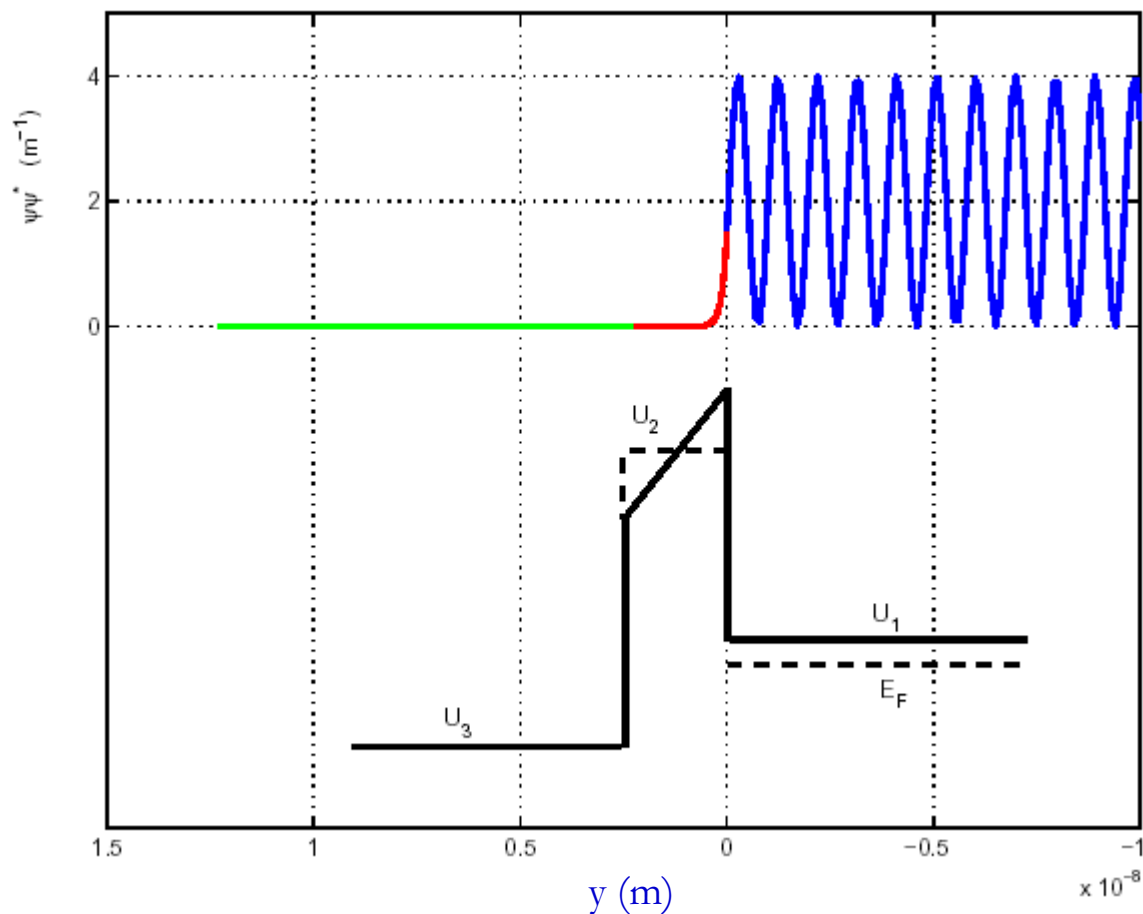
$$\psi_3 = Fe^{ik_3y},$$

Physically what is the "C-wave" ?

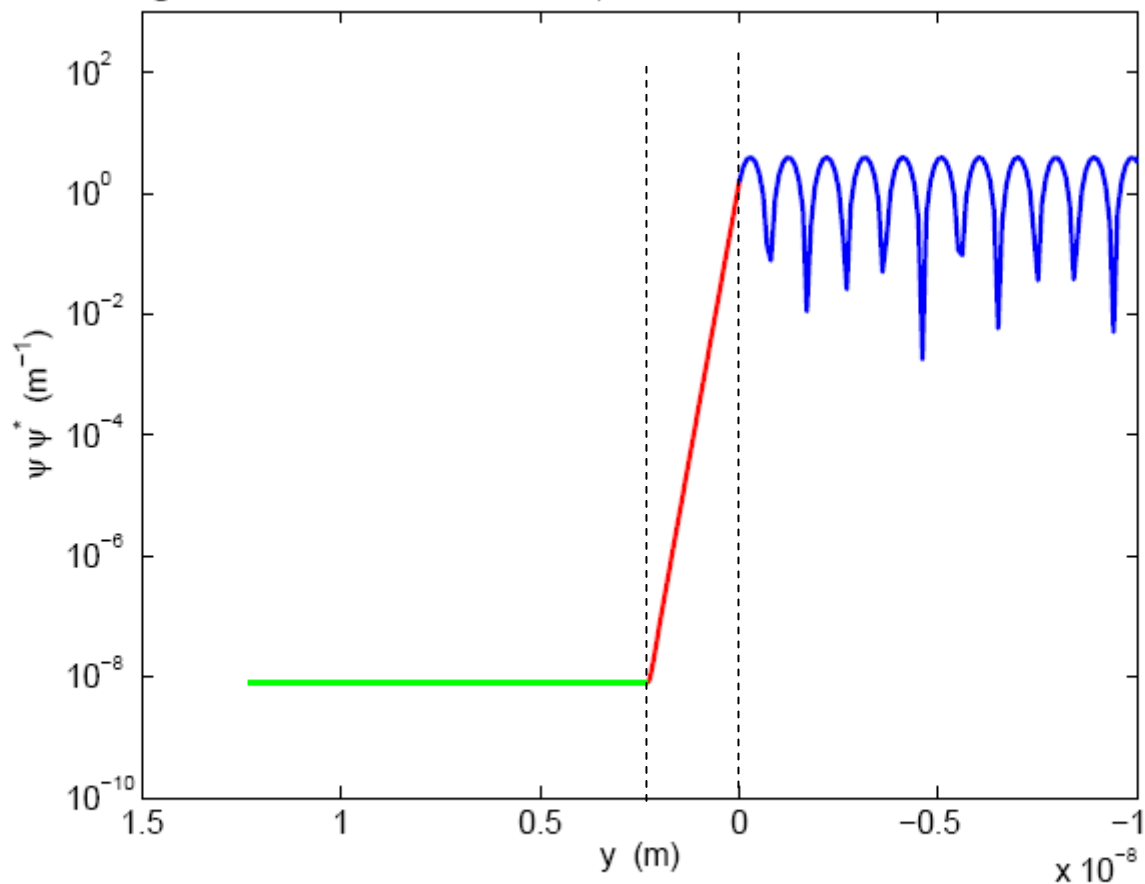
What is  $\psi \psi^*$  ?

Why is it :

- oscillatory in the channel ?
- damped in the oxide ?
- constant in the gate ?



# Emphasizing the reduction in $\psi \psi^*$



**Figure 5.9** Redrawing of the probability density from Fig. 5.8. The logarithmic scale emphasizes the small ( $\approx 10^{-8} \text{ m}^{-1}$ ) probability density of electrons tunneling from region 1.



# Probability Density Current

$$\begin{aligned}\frac{dP}{dt} &= \Psi^* \frac{\partial \Psi}{\partial t} + \Psi \frac{\partial \Psi^*}{\partial t} \\ &= \frac{1}{i\hbar} \left[ \Psi^* \left( i\hbar \frac{\partial \Psi}{\partial t} \right) + \Psi \left( i\hbar \frac{\partial \Psi^*}{\partial t} \right) \right]\end{aligned}$$

What does the flow of P mean ?

The time-dependent Schrödinger Wave Equation is

$$i\hbar \frac{\partial \Psi}{\partial t} = -\frac{\hbar^2}{2m^*} \nabla^2 \Psi + U\Psi$$

$$\begin{aligned}\frac{dP}{dt} &= -\frac{i\hbar}{2m^*} \nabla \cdot [\Psi \nabla \Psi^* - \Psi^* \nabla \Psi] \\ &\equiv -\nabla \cdot \vec{J}_P\end{aligned}$$

Do you recognize this as a Continuity Equation ?

# Transmission Probability: Definition

$$\begin{aligned}\frac{dP}{dt} &= -\frac{i\hbar}{2m^*} \nabla \cdot [\Psi \nabla \Psi^* - \Psi^* \nabla \Psi] \\ &\equiv -\nabla \cdot \vec{J}_P\end{aligned}$$

1. For the channel:

$$\psi_1 = Ae^{ik_1 y} + Be^{-ik_1 y}$$

2. Do the derivatives and the conjugates:

$$J_{P,A} = \frac{\hbar k_1}{m_1^*} |A|^2$$

$$J_{P,F} = \frac{\hbar k_3}{m_3^*} |F|^2$$

3. Define the Transmission Probability:

$$\begin{aligned}T(E) &= \frac{k_3 m_1^* |F|^2}{k_1 m_3^* |A|^2} \\ &\equiv \frac{v_{k,3} |F|^2}{v_{k,1} |A|^2},\end{aligned}$$

What do these mean ?

What is the interpretation of this ?

# Transmission Probability: Evaluation

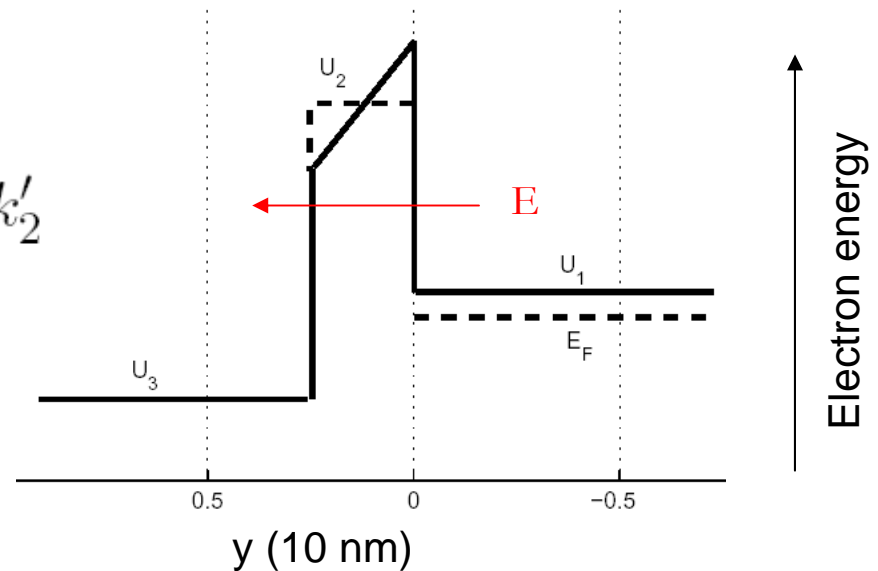
Solve for F and A:

$$T = \frac{4m_1k_3/m_3k_1}{(1 + k_3m_1/k_1m_3)^2 \cosh^2(k'_2d) + (k'_2m_1/k_1m_2 - k_3m_2/k'_2m_3)^2 \sinh^2(k'_2d)}$$

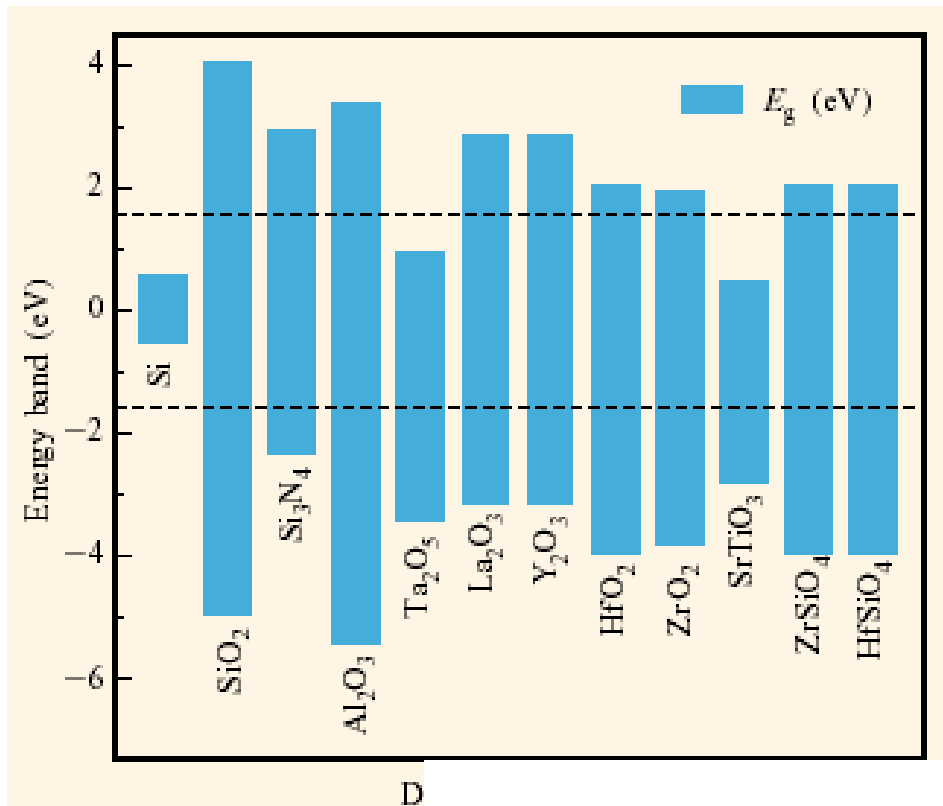
Identify the symbols with features on the band diagram. For example:

$$k_2 = \frac{1}{\hbar} \sqrt{2m_2^*(E - U_2)} \equiv ik'_2$$

What is important besides  $t_{ox}$  ?



# Silica vs. Hafnia: properties



	$\epsilon_r$	$t_{ox}$ (nm)	$\chi$ (eV)	$m^*$ ( $m_0$ )
Silica	3.9	2.3	0.9	0.3
Hafnia	$5\epsilon_{r,silica}$	$t_{ox}\epsilon_{r,hafnia}/\epsilon_{r,silica}$	2.9	0.1
Silicon	-	-	4.1	0.91

# The importance of electron affinity

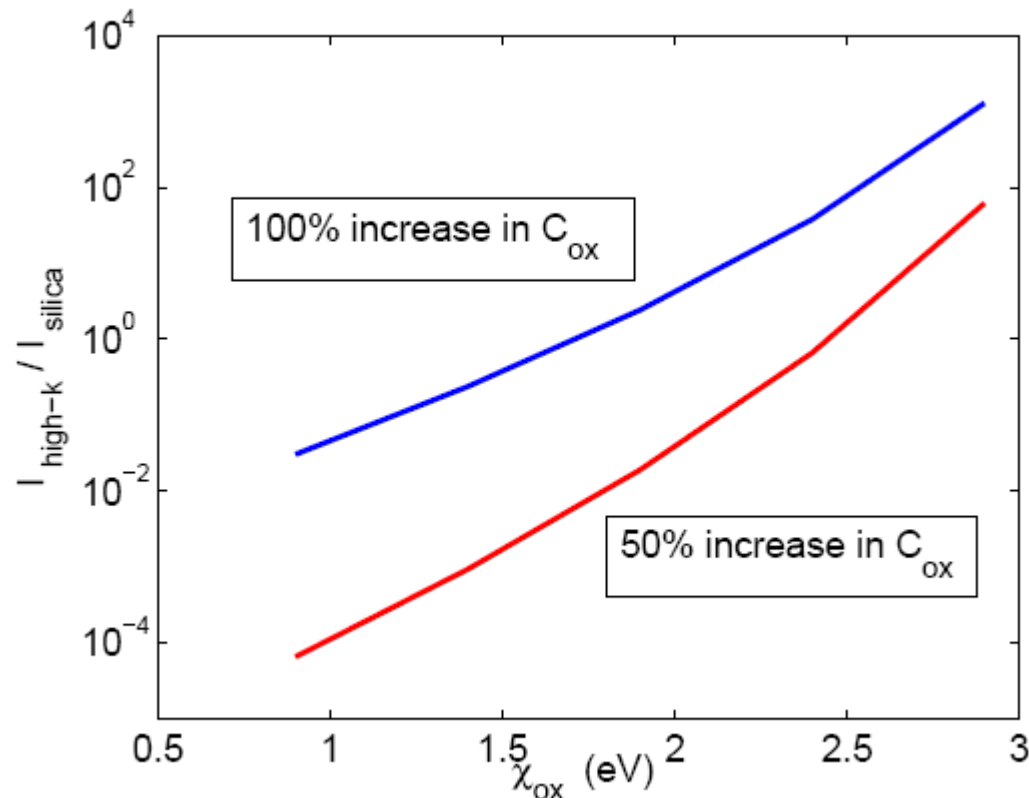


Figure 13.8: Ratio of tunnel current in a high-k dielectric to that in silica as a function of the electron affinity of the high-k dielectric. The high-k dielectric is taken to have a relative permittivity that is 4 times that of silica. The top curve is for an improvement in  $C_{ox}$  of 100%, and the bottom curve is for an improvement of 50%. The parameter values are as given in the caption to Fig. 5.9, unless otherwise stated.  $(E_{C,Si} - E_F)$  was taken to be 50 meV.

Is it possible to reduce  $I_{leak}$  and improve  $I_{ON}$  ?

# The new gate stack

## 45nm High-k + Metal Gate Strain-Enhanced CMOS Transistors

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Guess what Intel is doing

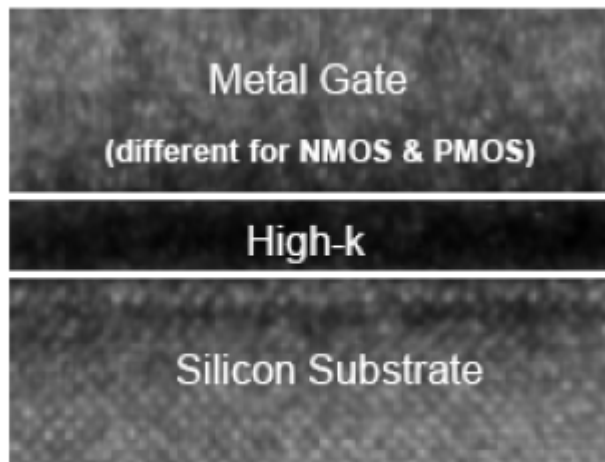


Figure 3: TEM of High-k/Metal gate stack

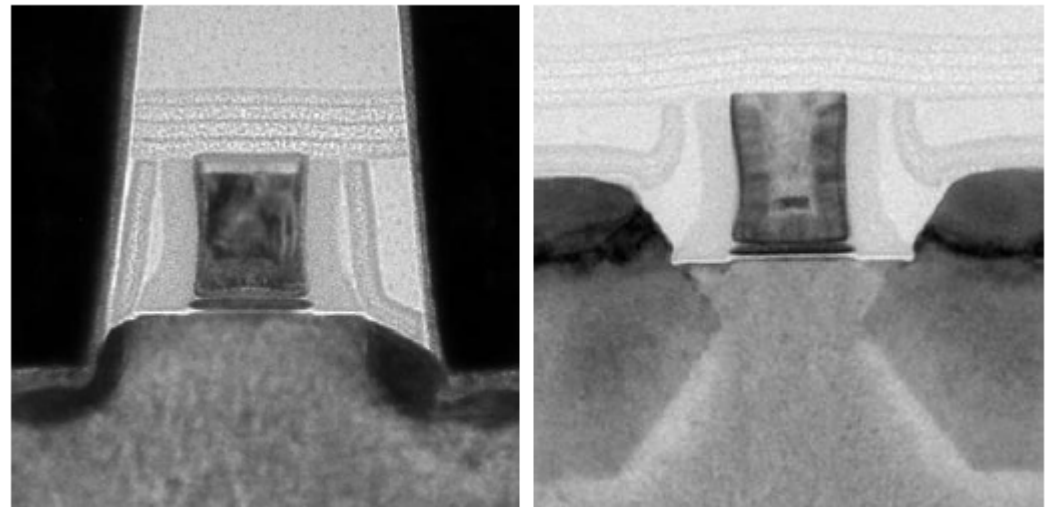
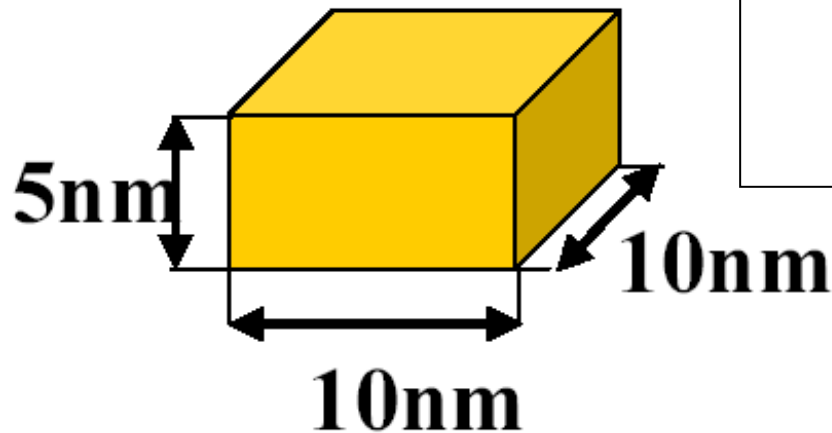


Figure 5: TEMs of High-k + Metal Gate NMOS (left) and PMOS (right) transistors

# Threshold voltage

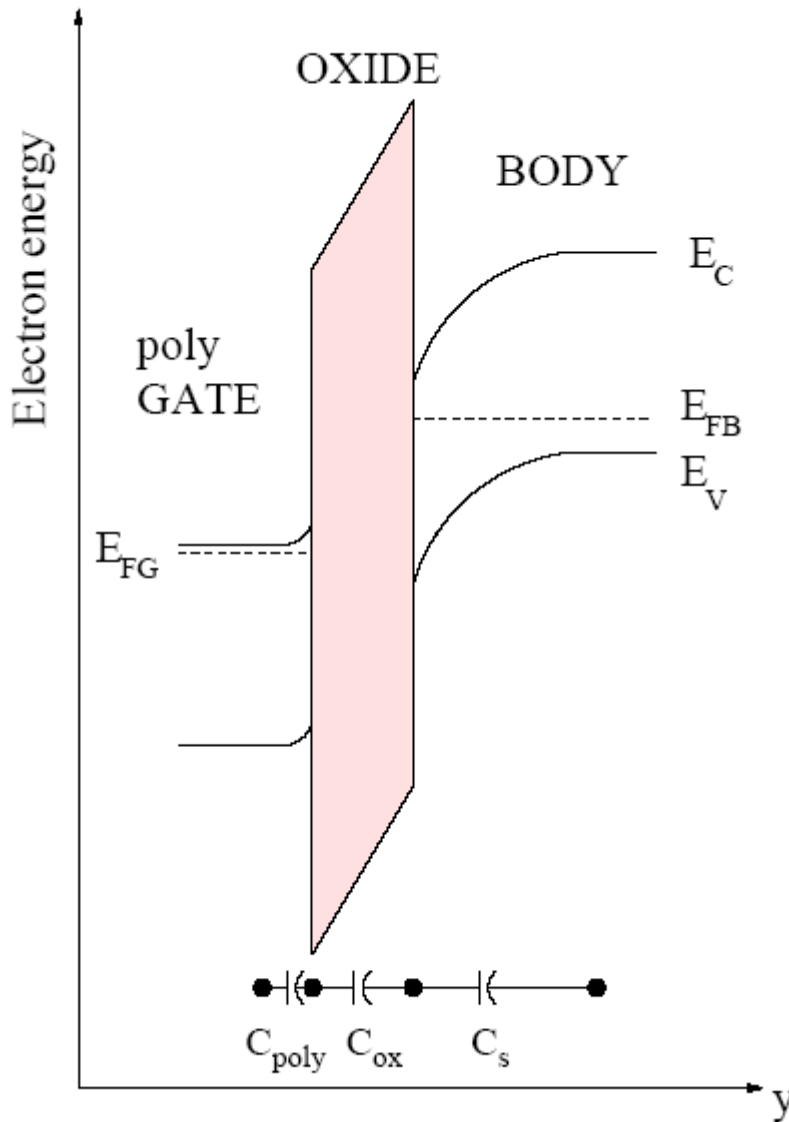
$$V_T \equiv V_{GS}^T = V_{fb} + 2\psi_B + \frac{1}{C_{ox}} \sqrt{2\epsilon_S q N_A (2\psi_B + V_{SB})}$$

What if  $N_A$  were greatly reduced?



- If  $V_T$  controlled by metal, perhaps can use undoped Si substrate.
- This would remove the problem of dopant fluctuations.
- But what about self-alignment?

# Another reason for metal gates



The finite conductivity of the poly-gate results in band bending in the gate.

$$V_{GB} - V_{fb} = \psi_{poly} + \psi_{ox} + \psi_s$$

How does this affect  $V_T$  ?